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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/777,026	02/11/2004	Mark N. Kawaguchi	8033/ETCH	2197	
55649 75	90- 10/31/2006		EXAM	EXAMINER	
MOSER IP LAW GROUP / APPLIED MATERIALS, INC. 1040 BROAD STREET			TRAN, BINH X		
2ND FLOOR	TREET		ART UNIT	ART UNIT PAPER NUMBER	
SHREWSBURY	Y, NJ 07702	1765			
			DATE MAILED: 10/31/2006		

Please find below and/or attached an Office communication concerning this application or proceeding.

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		Application No.	Applicant(s)	
Office Action Commence		10/777,026	KAWAGUCHI ET AL	- .
	Office Action Summary	Examiner	Art Unit	
		Binh X. Tran	1765	
<i> T.</i> Period for R	he MAILING DATE of this communication app eply	ears on the cover sheet with the c	orrespondence addr	'ess
A SHOR WHICHE - Extension after SIX (- If NO peri - Failure to Any reply	TENED STATUTORY PERIOD FOR REPLY VER IS LONGER, FROM THE MAILING DASS of time may be available under the provisions of 37 CFR 1.13 (6) MONTHS from the mailing date of this communication. Out for reply is specified above, the maximum statutory period we reply within the set or extended period for reply will, by statute, received by the Office later than three months after the mailing tent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 16(a). In no event, however, may a reply be tim ill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	N. nely filed the mailing date of this com D (35 U.S.C. § 133).	
Status				•
2a)⊠ Thi 3)⊡ Sir	sponsive to communication(s) filed on <u>11 Au</u> is action is FINAL . 2b) This ace this application is in condition for allowant sed in accordance with the practice under E	action is non-final. ace except for formal matters, pro		nerits is
Disposition	of Claims			
4a) 5)□ Cla 6)⊠ Cla 7)□ Cla	tim(s) <u>1-23 and 25-32</u> is/are pending in the at Of the above claim(s) is/are withdraw iim(s) is/are allowed. tim(s) <u>1-23, 25-32</u> is/are rejected. tim(s) is/are objected to. tim(s) are subject to restriction and/or	n from consideration.	•	
Application	Papers	·		
10)∐ The App Rep	specification is objected to by the Examiner drawing(s) filed on is/are: a) acception and acception to the objectment drawing sheet(s) including the correction oath or declaration is objected to by the Examiner	epted or b) objected to by the E rawing(s) be held in abeyance. See on is required if the drawing(s) is obj	e 37 CFR 1.85(a). ected to. See 37 CFR	
Priority unde	er 35 U.S.C. § 119		·	
a)∭ A 1.[2.[3.[_ , , , , , , , , , , , , , , , , , , ,	have been received. have been received in Application ty documents have been receive (PCT Rule 17.2(a)).	on No d in this National St	age
	References Cited (PTO-892) Draftsperson's Patent Drawing Review (PTO-948)	4)		
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Application/Control Number: 10/777,026 Page 2

Art Unit: 1765

DETAILED ACTION

Claim Rejections - 35 USC § 112

- 1. The following is a quotation of the second paragraph of 35 U.S.C. 112:
 - The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.
- 2. Claim 14 is rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

In line 1-2 of claim 14, "a forming gas" (emphasis added) is indefinite. It is unclear from the claim whether applicants wish to refer to the previous forming gas (in claim 9) or not. The examiner suggests replacing "a" with --the--.

Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 4. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to

Art Unit: 1765

consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).

5. Claims 1-23, 26-32 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chen et al. (US 5,545,289) in view of Belyansky et al. (US 6,562,713).

Respect to claims 1-2, 21 Chen discloses a method for removing halogen-containing residue from a substrate, (col. 5 lines 1-6), the method comprising the steps of:

providing an etched substrate having a halogen-containing residues, comprising at least chlorine (col. 5 lines 1-6; col. 6 lines 40-50)

heating the etched substrate to the temperature about 150°C to 400 °C (read on applicant's range of "at least 50 °C" and/or "50 °C to about 450 °C [claim 2]; See col. 8 lines 50-60);

exposing the heated substrate to a plasma that removes the halogen-containing residues, col. 6 lines 40-50; col. 8 lines 60-67, col. 13-14, Table I).

Chen fails to disclose the halogen-containing residue is formed during etching of a polysilicon layer on the substrate. However, Chen clearly discloses the halogen-containing residue (24) is formed during the etching step of layers on the substrate. Chen further discloses layer (28c) comprises silicon material (col. 4 lines 62-65). In a semiconductor process, Belyansky teaches to etch polysilicon layer to form a polysilicon gate using halogen gas (col. 3). Belyansky further discloses to the halogen-containing residue (bromine residue) remains after the etching of polysilicon layer can be easily removed using oxygen plasma (col. 4 lines 1-12). It would have been obvious to one

Art Unit: 1765

having ordinary skill in the art, at the time of invention, to modify Chen in view of Belyansky by etching a polysilicon layer using halogen-containing gas including bromine because the bromine residue can be easily removed after the etching step. Further, polysilicon layer is needed to form a polysilicon gate.

Respect to claims 3 and 23, Chen discloses forming the plasma by energizing a gas mixture in a remote plasma reactor (54) (See Fig 2). Respect to claims 4 and 26, Belyansky discloses the halogen-containing residue comprises bromine (col. 4 lines 3-12). Respect to claims 5 and 27, both Chen and Belyansky discloses the plasma comprises an oxygen-containing gas (Chen's Table 1; Belyansky's col. 4 lines 10-12). Respect to claims 6 and 28, Chen teaches to use oxygen plasma and an addictive comprises N₂ (Table I).

Respect to claims 7 and 29, Chen discloses the halogen-containing residue comprises chlorine (col. 5 lines 1-5). Respect to claims 8-9 and 30-31, Chen discloses the plasma comprises water vapor (i.e. hydrogen-containing gas), oxygen and nitrogen (See Table I in col. 13 and 14). Respect to claims 10 and 32, Chen discloses the heating step comprises heating the substrate in a gas mixture of oxygen and nitrogen (Table I). Respect to claim 11, Chen discloses the temperature of about 250 °C (Table I, example 2-6). Respect to claim 12, Chen teaches to use 3000 sccm of oxygen and 300 sccm of nitrogen (col. 13 lines 38-42). The flow ratio of oxygen to nitrogen equals to 3000:300 = 10:1.

Claim 13 further differs from Chen by the specific flow ratio of oxygen to hydrogen and hydrogen to water vapor. However, Chen clearly teaches to change the

Application/Control Number: 10/777,026

Art Unit: 1765

flow rate of individual gas and flow rate ratio are result effective variables (col. 7 lines 25-31, col. 8 lines 25-35, Table I, col. 13 lines 40-42, Table IV). The result effective variable is commonly determined by routine experiment. The process of conducting routine experiments so as to produce an expected result is obvious to one of ordinary skill in the art. Hence, it would have been obvious to one having ordinary skill in the art, at the time of invention, to perform routine experiment in order to obtain optimal flow rate ratio as an expected result.

Respect to claim 14, Chen discloses the passivating gas comprises 3000 sccm O_2 and 300 sccm NH_3 (read on applicant's forming gas). Respect to claims 15-16, Chen discloses the flow rate of water vapor is about 300 sccm (Table I, read on applicant's range of 100-3000 sccm) and the flow rate of oxygen is about 3000 sccm. The flow ratio of oxygen to water vapor equals to 3000 sccm/ 300 sccm = 10:1.

Respect to claims 17-18, Chen discloses the pressure of about 1-10 torr, preferably about 2 Torr (col. 6 lines 52-63) and the duration for the exposing step is about 40-60 seconds (table 1, example 1-2, 8).

Respect to claims 19-20, Chen discloses the pressure of about 1-10 torr, preferably about 2 Torr (col. 6 lines 52-63) and the duration for the exposing step is about 40-60 seconds (table I, example 1-2, 8).

Respect to claim 22, Chen discloses the temperature is between 200-250 °C (Table 1, read on applicant's range of 150-400 °C).

Application/Control Number: 10/777,026 Page 6

Art Unit: 1765

6. Claim 25 is rejected under 35 U.S.C. 103(a) as being unpatentable over Chen and Belyansky et al. as applied to claim 21 above, and further in view of Wu (US 6,133,102).

Respect to claim 25, Chen fails to disclose the etching the substrate having a film stack with a gas mixture comprising a halogen gas and a reducing gas. However, Chen and teaches to etch using halogen gas (BCl₃ and Cl₂). Belyansky clearly teaches to etch to etch polysilicon layer using halogen including Cl₂, Br₂, F₂ (See col. 3 lines 49-65) or HBr/O₂ (col. 4 lines 5-10). Wu teaches to polysilicon layer (120) by using halogen-containing gas (CF₄) in addition with hydrogen gas (read on reducing gas) or HBr/O₂ (col. 3 lines 41-51). It would have been obvious to one having ordinary skill in the art, at the time of invention, to modify Chen and Belyansky in view of Wu by using halogen gas and reducing gas (i.e. H₂) because equivalent and substitution of one for the other would produce an expected result.

Response to Arguments

7. Applicant's arguments with respect to the previous 35 USC 102 (b) or 102(e) rejection have been considered and are persuasive. Therefore, the previous grounds of rejections have been withdrawn. However, upon further consideration, a new ground(s) of rejection is made as discussed above.

Conclusion

8. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP

Art Unit: 1765

§ 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

9. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Binh X. Tran whose telephone number is (571) 272-1469. The examiner can normally be reached on Monday-Thursday and every other Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine Norton can be reached on (571) 272-1465. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should

Application/Control Number: 10/777,026 Page 8

Art Unit: 1765

you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

Binh X. Tran

DUY-VU N. DEO PRIMARY EXAMINER

4: Cond 10/06